TXC Corporation Product Introduction

Purpose

To introduce TXC's MO (MEMS Oscillator).

Objectives

- What is a MO
- Different BOM Structure between MO and XO
- Product Feature
- Product Advantage
- Target Application
- Manufacturing Flow
- TXC Core Competence

Content

8 pages

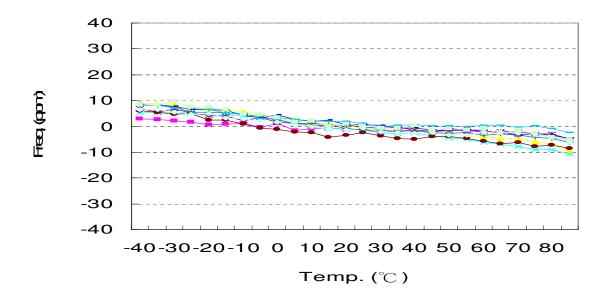
Learning Time

10 minutes



What is a MO?

- MO stands for "MEMS Oscillator"
- MEMS (micro-electrical mechanical system) based timing solutions
- Good frequency stability performance



Different BOM Structure

• A silicon based oscillator consist of a MEMS resonator with circuit IC molded in a plastic package different as quartz-base oscillator.

Single-end XO (Crystal)	BOM Structure	Single-end MO (Silicon)		
Quartz Crystal	Resonator	Silicon MEMS		
Fundamental 3rd Overtone PLL	IC	PLL Temperature- Compensated		
Ceramic Base Metal Lid	Package	Plastic Mold		
PIN to PIN Compatible				

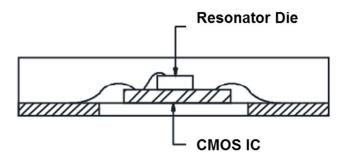
Product Advantage

	МО	XO
Lead Time	2-4 weeks	6-10 weeks
Inventory Management	Integrated to one die	Multi-materials, Quartz blank, IC, lid, substrate
Quality	Excellent Entire auto-production	Good Well-controlled to avoid particle
Robustness	50,000G	2,000G
Stability over operation temp.	Linear curve, Temperature compensation to get high stability	Curve of second degree, quartz easy to be affected by temperature
Package size	7050/5032/3225/2520 cover 1~150MHz	Frequency range is different in 7050/5032/3225/2520/2016
High frequency	Up to 800MHz	Need filter design for 150MHz above
Packaging	Plastic QFN molding, No dependency on ceramic package allocation	Ceramic + Metal Lid

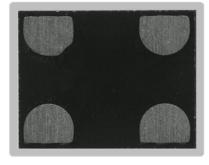
Product Feature

Oscillator	Product Series	Frequency Range	Feature	Oscillation
TZZHOZA ROZZA	T Series (MO) (7050/5032/3225/2520)	1 ~ 150MHz	±25ppm / ±50ppm -40 ~ 85°C 1.8 ~ 3.3V	PLL (Silicon)

MO (Silicon based MEMS Oscillator) ideal for PC, Tablet, HDD, DSC, STB, Server, Storage, Networking







Top view

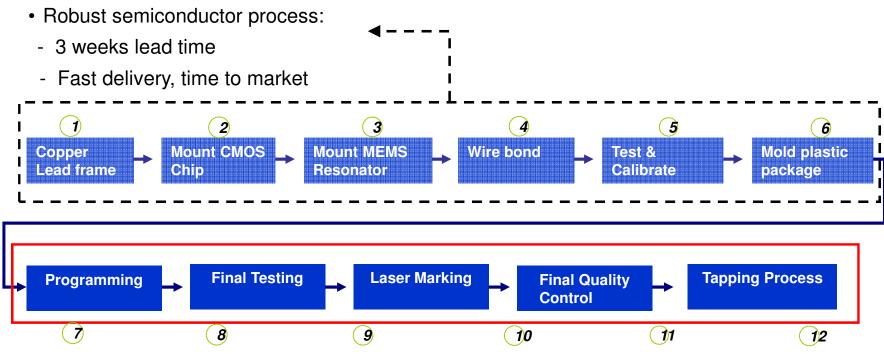
Bottom view

Target Application

MO is ideal for the following wired applications

Applications	Common Frequency (MHz)	Value
GPON/EPON	25, 32.768, 66, 125	Shock & Vibration resistance
Ethernet/Switch/ Network appliances	25, 25.000625, 33, 48, 50, 66.666,100, 125	Pin-to-pin replacement of quartz
Server SATA/SAS	33, 50, 66.667, 75, 100, 133.33	Excellent stability over operation temperature
Tablet, SSD	5, 12, 24, 22.5792, 26, 38.4, 48, 50	2-4 weeks lead time
DSC	12, 24, 40.5, 72	Low power
STB	12.2, 27, 50	Small size
DVR/IP cam	12.288, 24, 25, 27, 33, 36, 50, 54,	Competitive cost

Manufacturing Flow



- In-house programming and quality inspection process
- 100% quality assurance
- Standard is 3 weeks, with rolling forecast can be 1 week, rush case can be discussed.

TXC Core Competence

Technology

In-House Programming, Simulation, and Processing Capabilities

Quality

Assurance on Design and Production

Service

Global Sales, Marketing and FAE Support

Cost Efficiency

Economy of Scale Production in both Taiwan and China Factories

Time to Market

Leader in Crystal & Oscillator Miniaturization

Flexibility

Agile Sampling Capability and Quick Ramp Up to Volume

